562/564 Series

Circuit Board Mount Blocks for TE5/TR5 Type Fuses

RoHS





564 Series Holder

Additional Information



Resources 562 Series



Resources 564 Series



Accessories 564 Series



Samples 562 Series



Samples 564 Series



	562 Series	564 Series	
Compatible Fuses	TR5/TE5		
Materials	Block: Black Thermoplastic, UL94 V-0 PET		
	Terminals: Copper alloy; solderable tinned		
Electrical Data (23°C)	Rated Voltage: 250V		
	Max. Current/Power: 6.3A/1.6W		
Mounting	PC Board,	PC Board,	
	5.08mm pin spacing	5.08mm pad spacing	
Minimum Cross	Conducting path -	Conducting path -	
Section	0.1mm ²	0.1mm ²	
Unit Weight	0.12g	0.44g	
Ambient Temperature	- 40°C to + 85°C		

Ordering Information

Ordering Number	Circuit Board Mounting	Packaging
56200001009	Thru-Hole	1000 (Bulk pack)
56400001009	Surface Mount	1500 (Tape /Reel)

Agency Approvals

Agency	Agency File Number	
	562 Series	564 Series
91	E14721	E14721

Dimensions units in mm

562 Series Holder





564 Series Holder





Soldering Parameters - Wave Soldering



Soldering Parameters - Reflow Soldering

Reflow Condition		Pb - Free assembly
Number of allowed reflow cycles		3
Pre Heat	-Temperature Min (T _{s(min)})	150°C
	-Temperature Max (T _{s(max)})	200°C
	-Time (Min to Max) (t _s)	60 - 120 Secs.
Average ramp up rate (Liquidus Temp ($\mathbf{T}_{\rm L}$) to peak		5°C/second max.
T _{s(max)} to T _L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	-Temperature (t _L)	60 - 150 seconds
Peak Temperature (T _P)		240+/-5 °C
Time within 5oC of actual peak Temperature $(t_{\mbox{\tiny p}})$		30 secs. max.
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T _P)		8 minutes max.
Do not exceed		245°C

Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation	
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)	
Temperature Minimum:	100°C	
Temperature Maximum:	150°C	
Preheat Time:	60-180 seconds	
Solder Pot Temperature:	260°C Maximum	
Solder Dwell Time:	2-5 seconds	

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C

Heating time: 5 seconds max **Note:** These devicess are not recommended for IR and Convection Reflow process



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at: www.littelfuse.com/disclaimer-electronics.



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Littelfuse:

56400001009 56200001009